

Bluetooth Qualified Product Listing Notice

BQB: Mike Lu

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Number of annexes: 1

Applicant details

Applicant	MITSUMI Electric Co., Ltd.	Person responsible	Seiichi Sakurai
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Product identification

Brand name	Mitsumi	Hardware versions	1
Product name	Bluetooth Module		
Product ID	WML-C40##	Software versions	19.2
Product category	Hardware Integrated Component		

Description	Bluetooth Class 1 module with 2.0+EDR specification.
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Reference documents

Bluetooth specifications	Version 2.0+EDR
Test Case Reference List	TCRL Release date: 2005-05-01 Addendum Release date: N/A
Qualification Program Reference Document	Version 1.0 and 1 st Addendum dated 2004-04-23

Bluetooth Product Listing identification

QPLN Ref. No	Q30106_WMLC40_SGS	Assessment date	2006-03-01
		Listing date	2006-03-01

This notice is an essential part of the Bluetooth Qualification program and shows the acceptance of this product as a qualified Bluetooth product. On the basis of the reviewed submitted compliance folder for the above mentioned product, I certify that the product has passed all requirements to be listed as qualified Pre-tested Component in accordance to section 6.2.1 of the PRD.

Taipei, 2006-03-01

Place, date

Original is signed

Signature

Annex 1 to Bluetooth Qualified Product Listing Notice

1) Covered Functionality

The covered functionality of this product is defined as follows:

1.- RF part as defined in Volume 2,Part A of the Bluetooth Core Specification, Version 2.0 +EDR(Class 1 Operation) including all mandatory and optional features except power control.(Associate PICS RF.ICS/2.0.E.0).

In addition, RF covered functionality applies under the following conditions:

- Normal temperature: 25°C
- Temperature range: -40 °C to +70 °C
- Nominal voltage: +3.3V
- Voltage range: +3.2V to +3.4V
- Oscillator: Internal
- Maximum Antenna gain: 2.00 dBi

2.- BB part as defined in Volume 2,Part B of the Bluetooth Core Specification, Version 2.0 +EDR and specified in the covered functionality of the Software Integrated Component (Bluetooth Identifier: B01868) (Associate PICS BB.ICS/2.0.E.0)

3.- LMP part as defined in Volume 2,Part C of the Bluetooth Core Specification Version 2.0 +EDR and specified in the covered functionality of the Software Integrated Component (Bluetooth Identifier: B01868),Associate PICS LM.ICS/2.0.E.1.

4.- Host Controller Interface (HCI) as defined in Part E to the Bluetooth Specification Version 2.0+EDR.

5.- UART Transport Layer as defined in Bluetooth Ver. 1.1 Vol. 1 Part H:4 to the Bluetooth Specification Version 1.2.

6.- USB Transport Layer as defined in Bluetooth Ver. 1.1 Vol. 1 Part H:2 to the Bluetooth Specification Version 1.2.

2) Hardware Reference Platform

The module was mounted on a transit board connect to CSR development kit Casira which provided necessary interfaces for testing.

3) Notes

The covered functionality is applicable when implemented the guidelines provided by the manufacturer in the Reference Integration Note and technical specification available from the manufacturer.

When this component is integrated in another product, re-testing of RF performance may be considered in accordance with the latest BTAB RF guideline.

4) Integrated Pre-tested Components

The product integrates the following pre-tested components:

Bluetooth Identifier: B01867
Product ID: BC4-Ext
Product Type: Hardware Integrated Component

Bluetooth Identifier: B01868
Product ID: HCISStack2.0EDR
Product Type: Software Integrated Component

5) Revision history

Date	Reference	Comment
2006-03-01	Q30106_WMLC40_SGS (ver1.0)	First issue